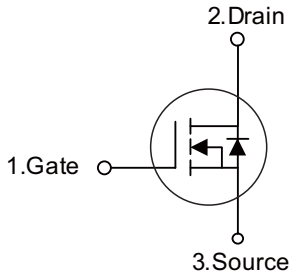
■ PRODUCT CHARACTERISTICS

VDSS	60V
R_{DS}(on)max(@V_{GS} =10 V)	18mΩ
ID	50A

Symbol

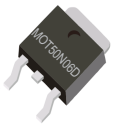


■ APPLICATIONS

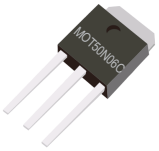
* Switching applications

■ FEATURES

* $R_{DS(ON)}$ ≤18m Ω @ V_{GS}=10V, I_D=25A
* High Switching Speed
* Improved dv/dt capability



TO-252



TO-251

■ ORDER INFORMATION

Order codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT50N06D	TO-252	2500 pieces /Reel
N/A	MOT50N06C	TO-251	70 pieces/Tube

■ ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	60	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current		I_D	50	A
Pulsed Drain Current (Note 2)		I_{DM}	150	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	92	mJ
Peak Diode Recovery dv/dt		dv/dt	10	V/ns
Power Dissipation	TO-251/TO-252	P_D	46	W
Junction Temperature		T_J	+150	°C
Operation and Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature.
3. L=43mH, I_{AS}=43A, V_{DD}=25V, R_G=20Ω, Starting T_J=25°C
4. I_{SD} ≤ 30A, V_{DS}=0V, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-251/TO-252	θ_{JA}	100	°C/W
Junction to Case	TO-251/TO-252	θ_{JC}	2.7 (Note)	°C/W

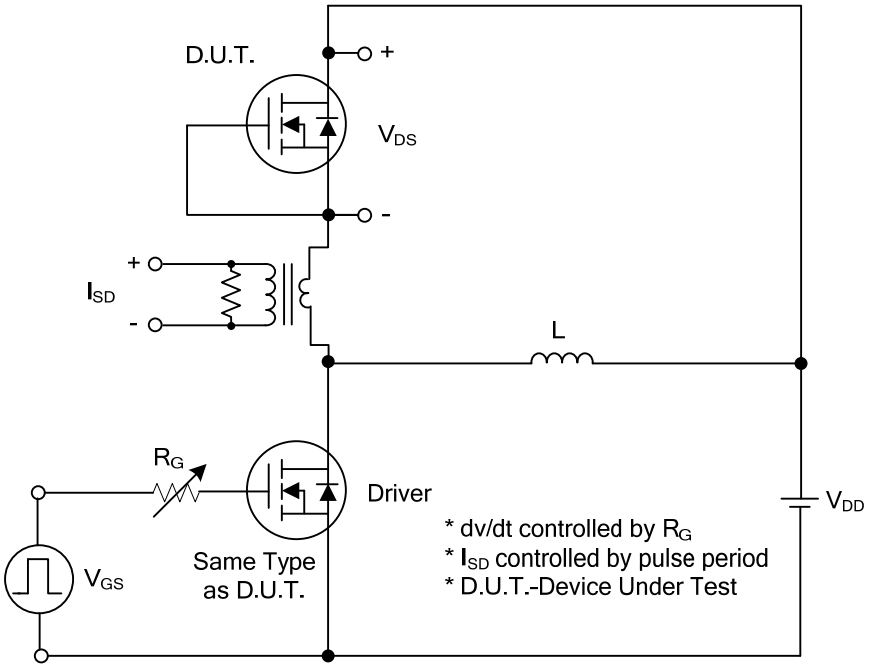
Note: The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.

■ ELECTRICAL CHARACTERISTICS (T_C=25°C, unless otherwise specified)

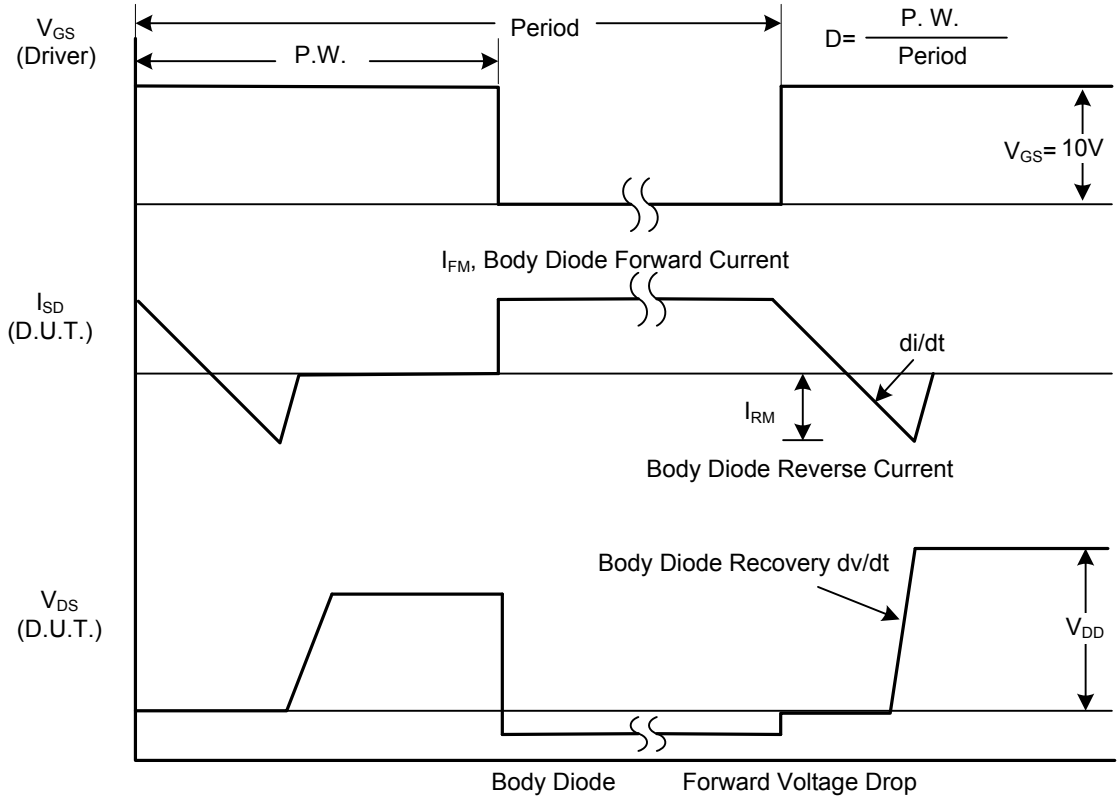
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS}=0V, I_D=250μA	60			V
Drain-Source Leakage Current		I_{DSS}	V_{DS}=60V, V_{GS}=0V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS}=20V, V_{DS}=0V			100	nA
	Reverse		V_{GS}=-20V, V_{DS}=0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS}=V_{GS}, I_D=250μA	1.0		2.5	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS}=10V, I_D=25A			18	mΩ
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{ISS}	V_{GS}=0V, V_{DS}=25V, f=1MHz		2500		pF
Output Capacitance		C_{OSS}			230		pF
Reverse Transfer Capacitance		C_{RSS}			200		pF
SWITCHING CHARACTERISTICS							
Total Gate Charge		Q_G	V_{DS}=50V, V_{GS}=10V, I_D=1.3A I_G=3mA (Note1,2)		7.2		nC
Gate-Source Charge		Q_{GS}			0.4		nC
Gate-Drain Charge		Q_{GD}			0.8		nC
Turn-On Delay Time		$t_{D(ON)}$	V_{DS}=30V, V_{GS}=10V, I_D=50A, R_G=25Ω (Note1,2)		18		ns
Turn-On Rise Time		t_R			46		ns
Turn-Off Delay Time		$t_{D(OFF)}$			202		ns
Turn-Off Fall Time		t_F			116		ns
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS							
Maximum Continuous Drain-Source Diode Forward Current		I_S				50	A
Maximum Pulsed Drain-Source Diode Forward Current		I_{SM}				150	A
Drain-Source Diode Forward Voltage		V_{SD}	I_S=50A, V_{GS}=0V			1.5	V
Body Diode Reverse Recovery Time		t_{rr}	I_S=30A, V_{GS}=0V, dI_S/dt=100A/μs		50		ns
Body Diode Reverse Recovery Charge		Q_{rr}			80		nC

Notes: 1. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS



Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

■ TEST CIRCUITS AND WAVEFORMS(Cont.)

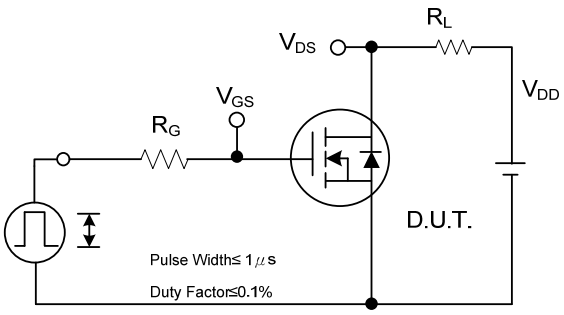


Fig. 2A Switching Test Circuit

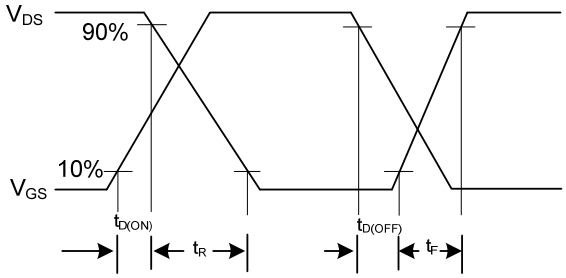


Fig. 2B Switching Waveforms

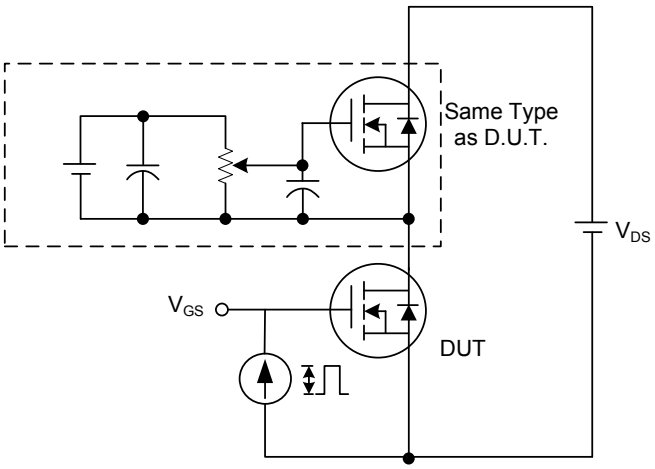


Fig. 3A Gate Charge Test Circuit

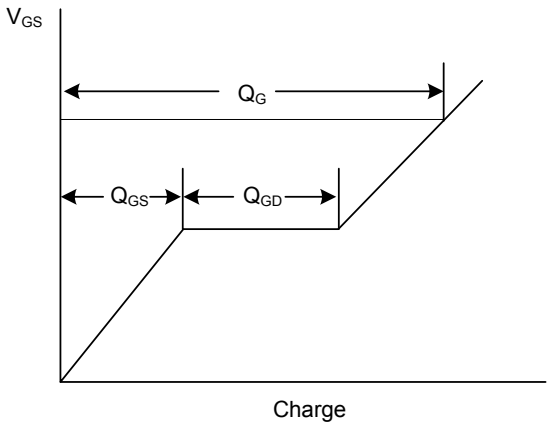


Fig. 3B Gate Charge Waveform

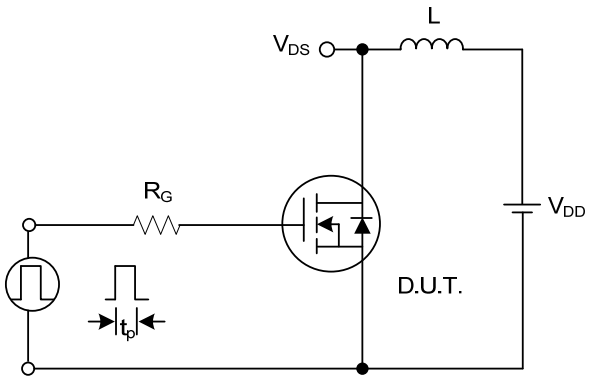


Fig. 4A Unclamped Inductive Switching Test Circuit

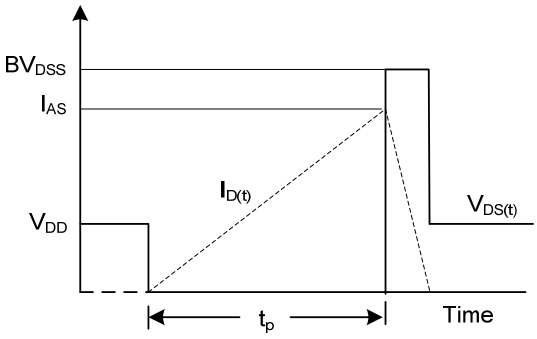
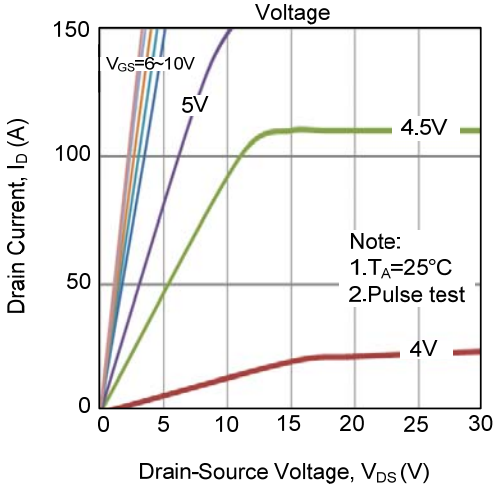


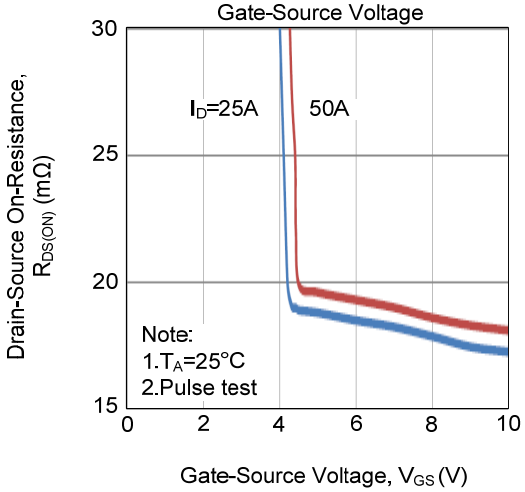
Fig. 4B Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

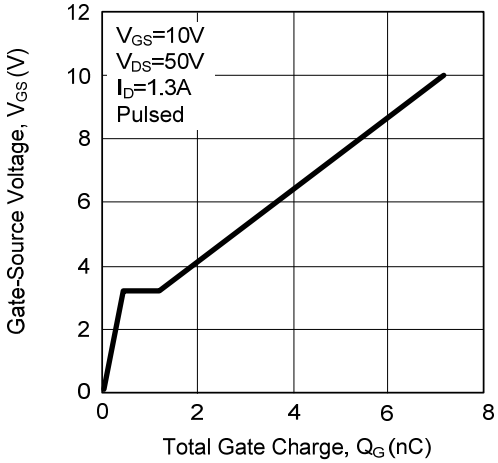
Drain Current vs. Drain-Source Voltage



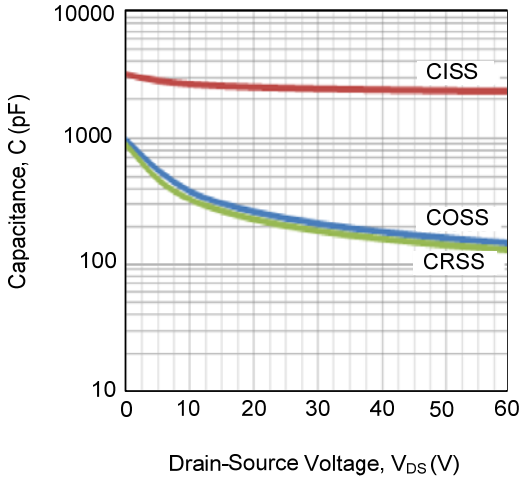
Drain-Source On-Resistance vs. Gate-Source Voltage



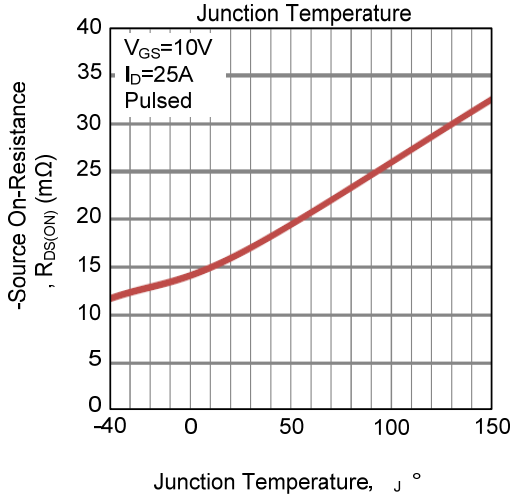
Gate Charge Characteristics



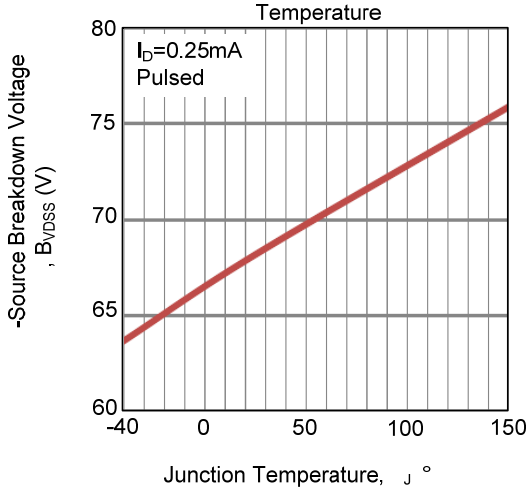
Capacitance Characteristics



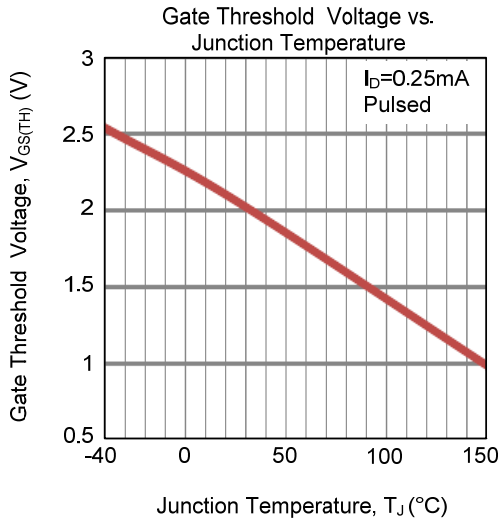
Drain-Source On-Resistance vs. Junction Temperature

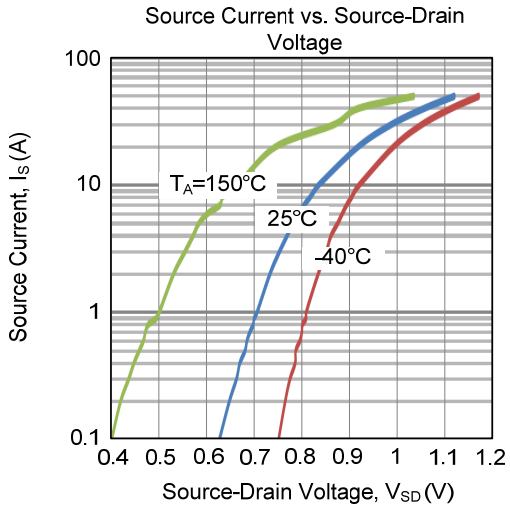


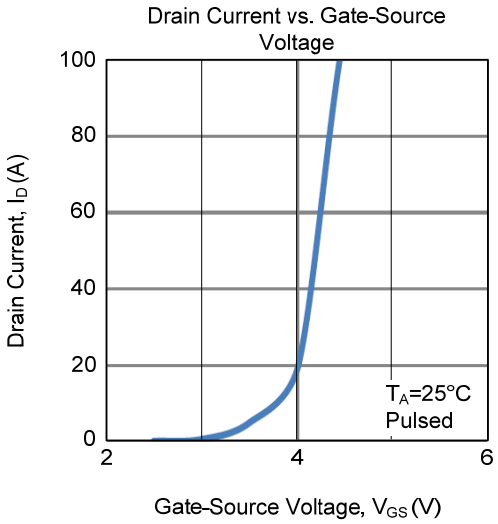
Breakdown Voltage vs. Junction Temperature

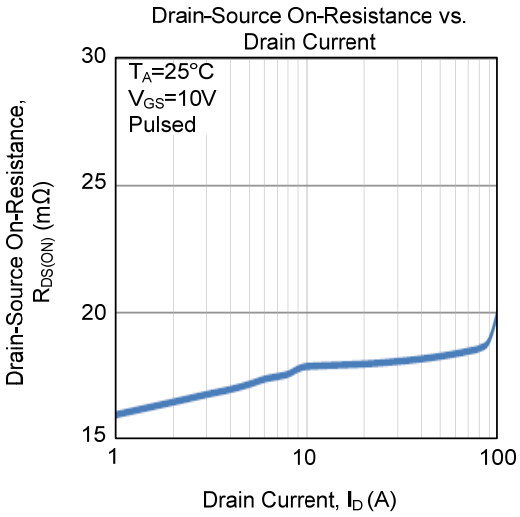


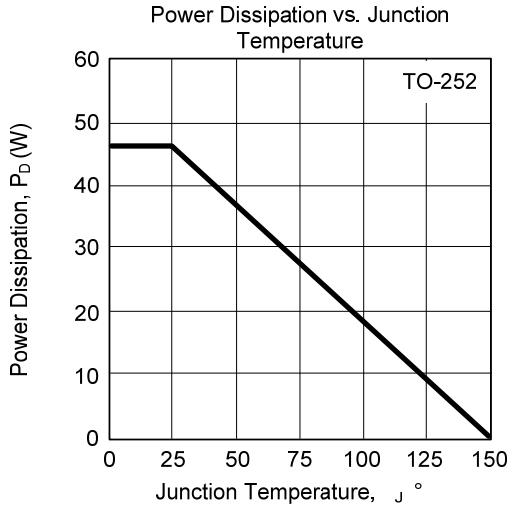
■ TYPICAL CHARACTERISTICS(Cont.)

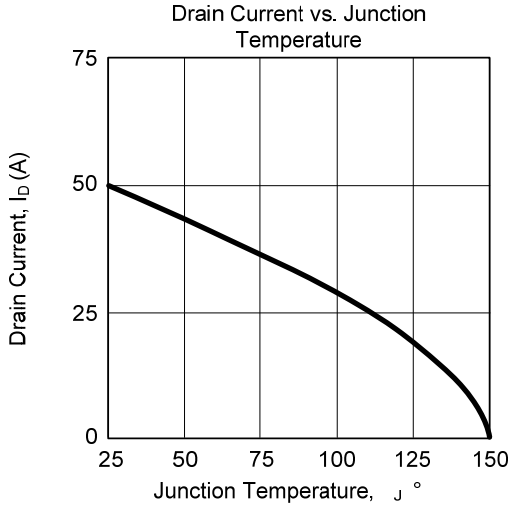




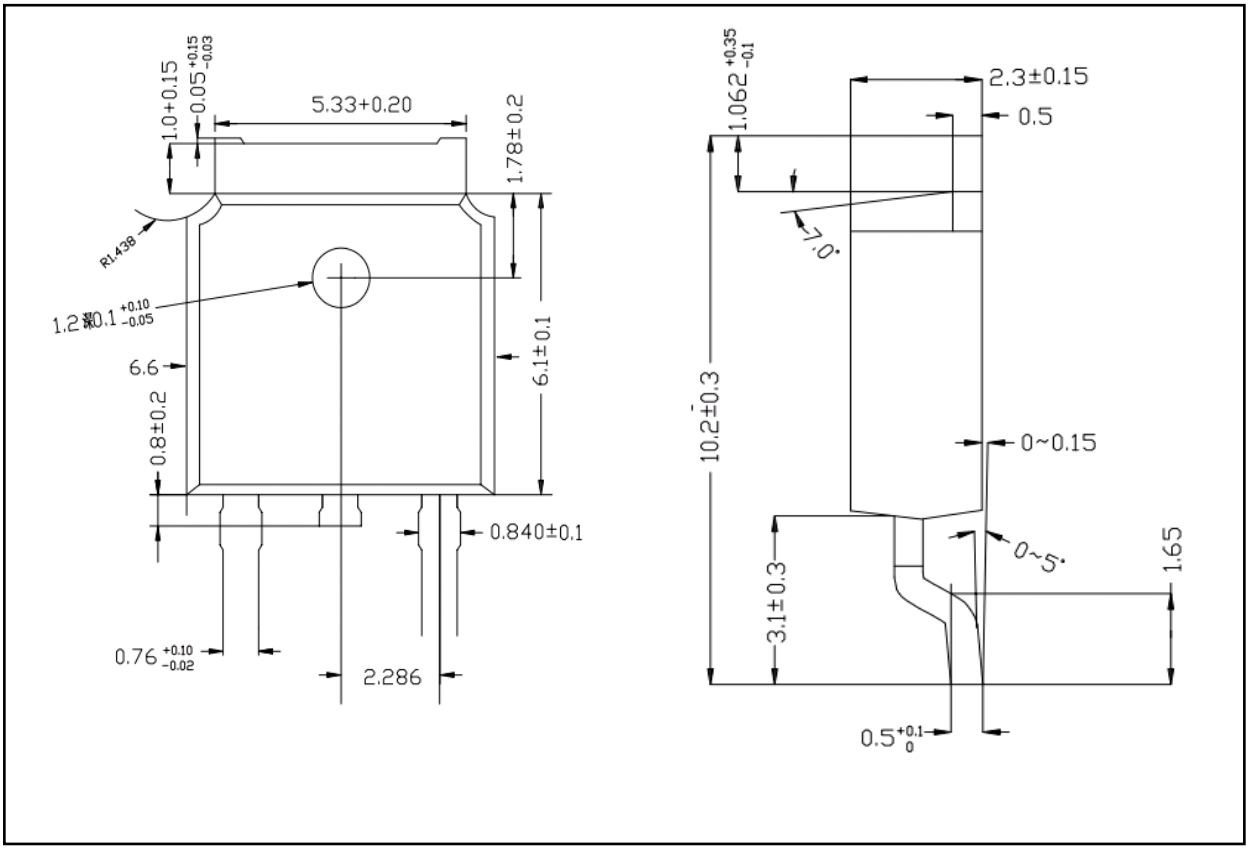








■ TO-252 PACKAGE OUTLINE DIMENSIONS



■ TO-251 PACKAGE OUTLINE DIMENSIONS